

1. General description

Planar passivated high commutation three quadrant triac in a SOT78 (TO-220AB) plastic package intended for use in circuits where high static and dynamic dV/dt and high dI/dt can occur. This "series BT" triac will commutate the full RMS current at the maximum rated junction temperature ($T_{j(max)} = 150^\circ\text{C}$) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

2. Features and benefits

- 3Q technology for improved noise immunity
- High commutation capability with maximum false trigger immunity
- High immunity to false turn-on by dV/dt
- High junction operating temperature capability
- High voltage capability
- Least sensitive gate for highest noise immunity
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only

3. Applications

- Applications subject to high temperature
- Electronic thermostats (heating and cooling)
- Motor controls e.g. washing machines and vacuum cleaners
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids

4. Quick reference data

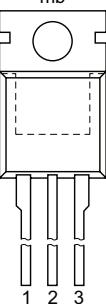
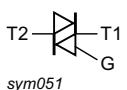
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DRM}	repetitive peak off-state voltage			-	-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 131^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3		-	-	10	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25^\circ\text{C}$; $t_p = 20\text{ ms}$; Fig. 4 ; Fig. 5		-	-	100	A

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T2+ G+ T _j = 25 °C; Fig. 7		2	-	50	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G- T _j = 25 °C; Fig. 7		2	-	50	mA
		V _D = 12 V; I _T = 0.1 A; T2- G- T _j = 25 °C; Fig. 7		2	-	50	mA
Dynamic characteristics							
dV _D /dt	rate of rise of off-state voltage	V _{DM} = 536 V; T _j = 150 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit		1000	-	-	V/μs
dI _{com} /dt	rate of change of commutating current	V _D = 400 V; T _j = 150 °C; I _{T(RMS)} = 10 A; dV _{com} /dt = 20 V/μs; (snubberless condition); gate open circuit		20	-	-	A/ms

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		
2	T2	main terminal 2		
3	G	gate		
mb	T2	mounting base; main terminal 2		

6. Ordering information

Table 3. Ordering information

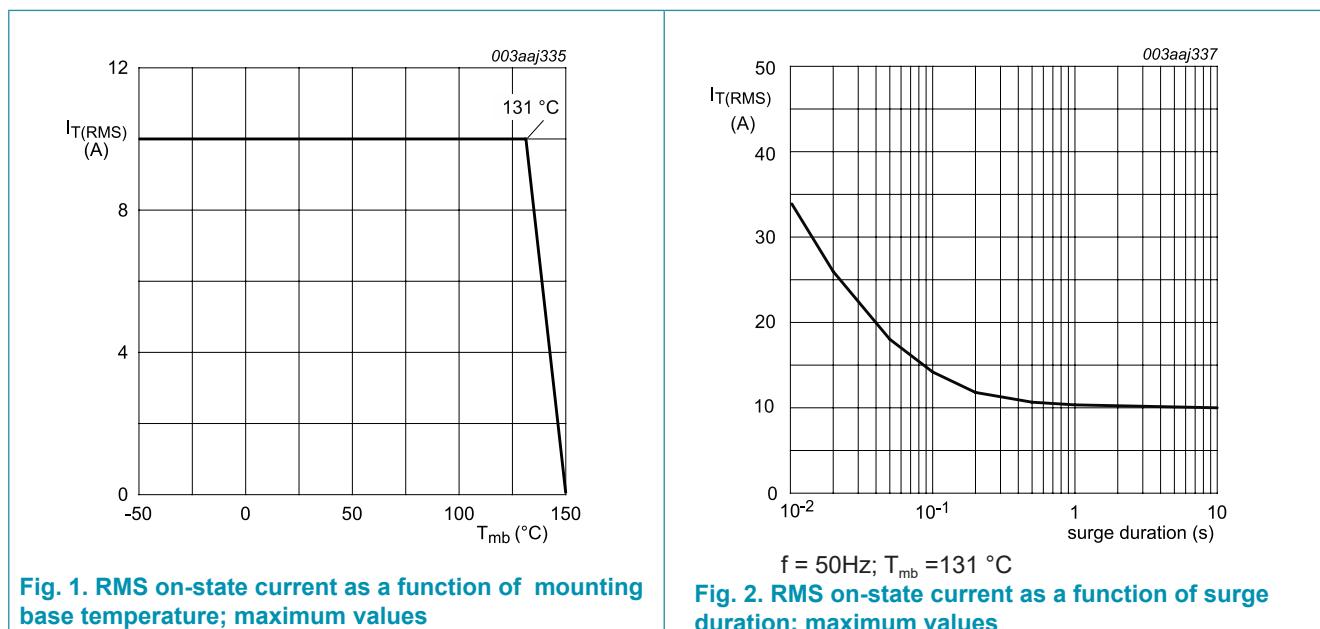
Type number	Package			Version
	Name	Description		
BTA410-800BT	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB		SOT78

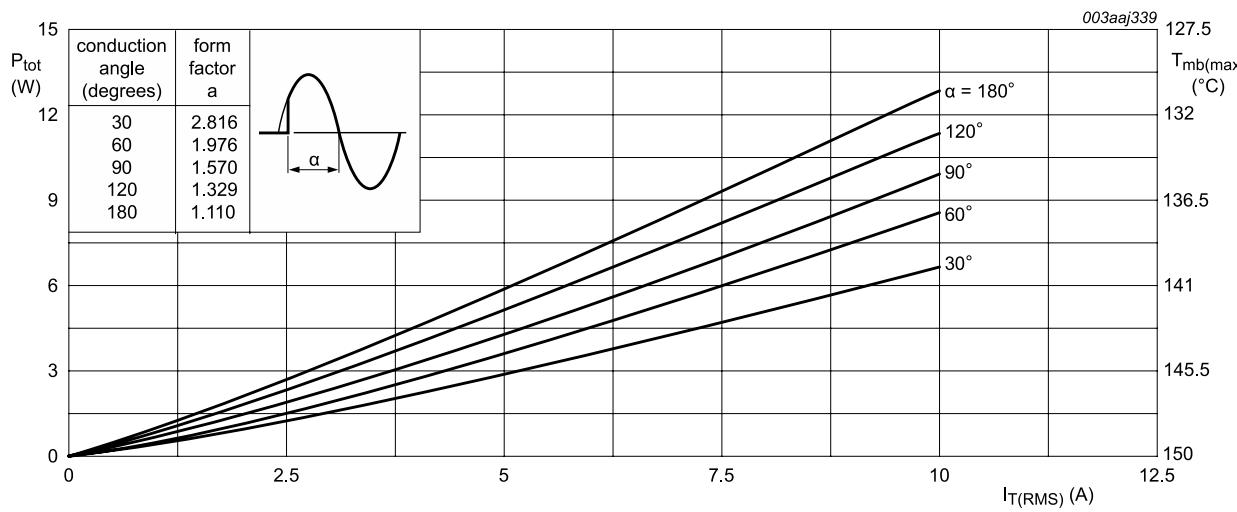
7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

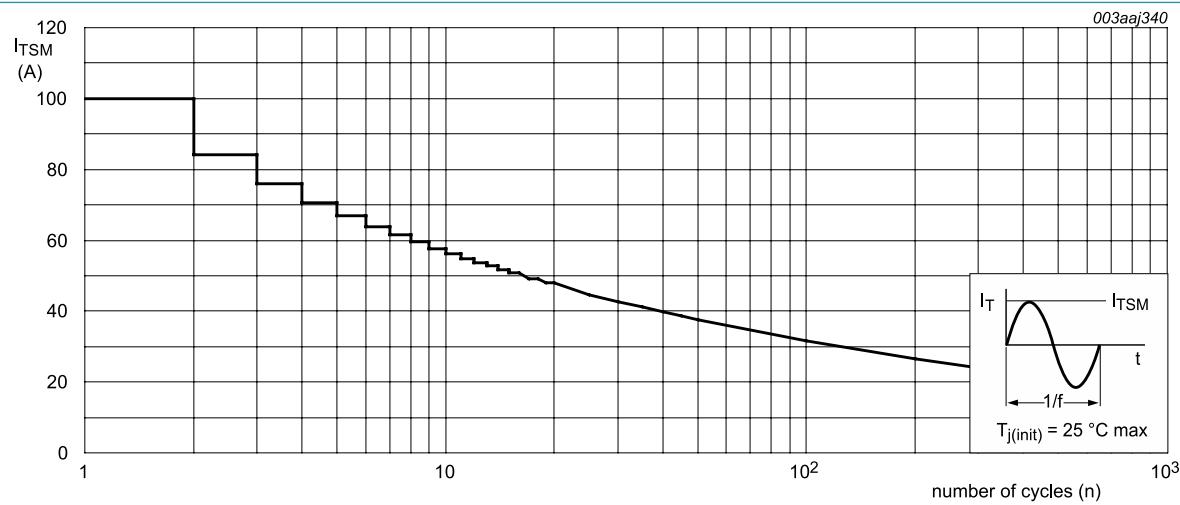
Symbol	Parameter	Conditions		Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage			-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 131^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3		-	10	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25^\circ\text{C}$; $t_p = 20\text{ ms}$; Fig. 4 ; Fig. 5		-	100	A
		full sine wave; $T_{j(init)} = 25^\circ\text{C}$; $t_p = 16.7\text{ ms}$		-	110	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; sine-wave pulse		-	50	A^2s
dI/dt	rate of rise of on-state current	$I_G = 100\text{ mA}$		-	100	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current			-	2	A
P_{GM}	peak gate power			-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period		-	0.5	W
T_{stg}	storage temperature			-40	150	$^\circ\text{C}$
T_j	junction temperature			-	150	$^\circ\text{C}$





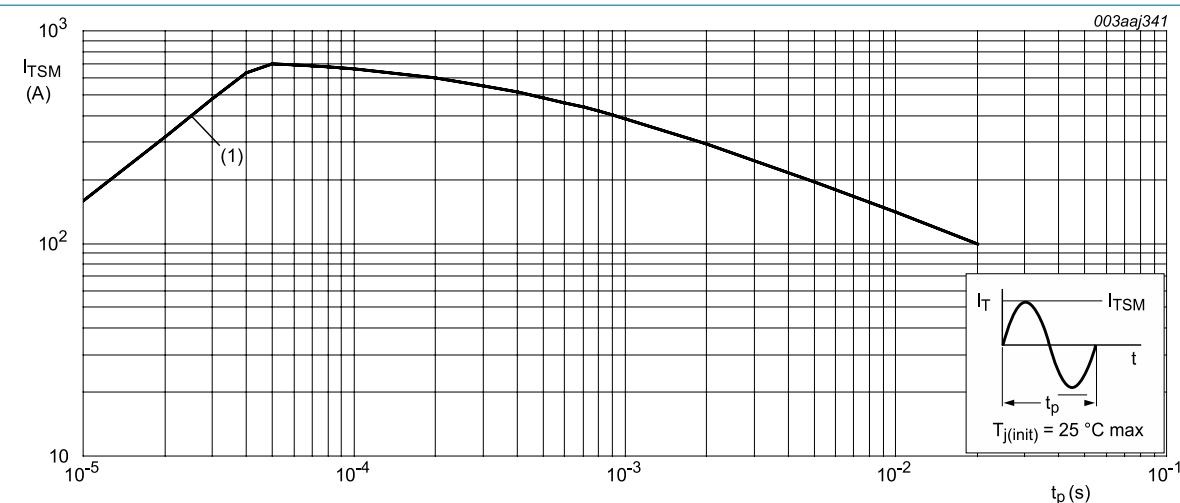
α = conduction angle
 a = form factor = $I_{T(\text{RMS})} / I_{T(\text{AV})}$

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



$f = 50 \text{ Hz}$

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 20 \text{ ms}$;
(1) dI_T/dt limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse duration; maximum values

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	full cycle; Fig. 6		-	-	1.5	K/W
		half cycle; Fig. 6		-	-	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		-	60	-	K/W

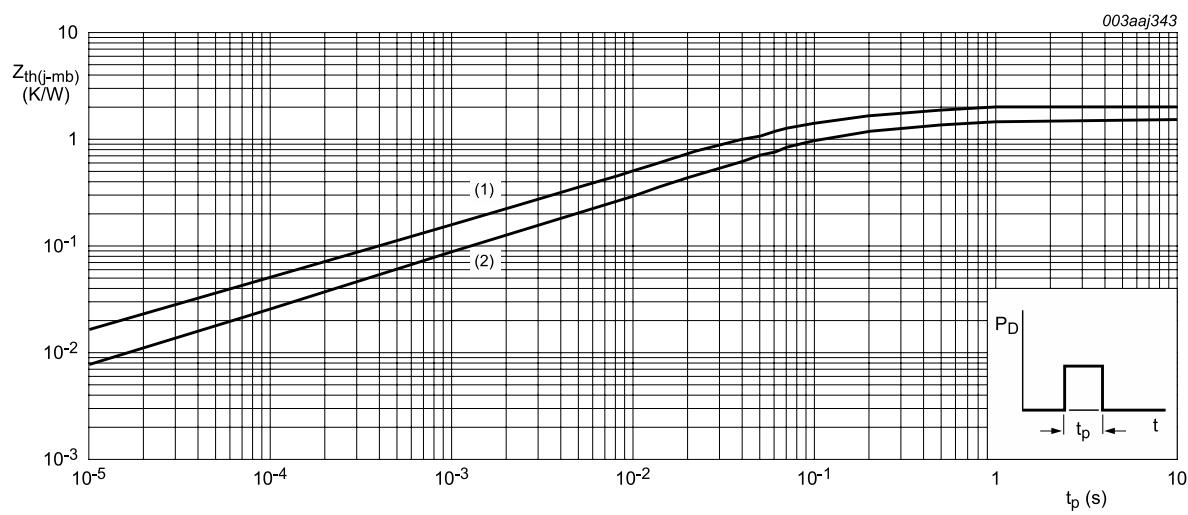


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_2+ G+; T_j = 25^\circ\text{C};$ Fig. 7		2	-	50	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_2+ G-; T_j = 25^\circ\text{C};$ Fig. 7		2	-	50	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_2- G-; T_j = 25^\circ\text{C};$ Fig. 7		2	-	50	mA
I_L	latching current	$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_2+ G+; T_j = 25^\circ\text{C};$ Fig. 8		-	-	60	mA
		$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_2+ G-; T_j = 25^\circ\text{C};$ Fig. 8		-	-	90	mA
		$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_2- G-; T_j = 25^\circ\text{C};$ Fig. 8		-	-	60	mA
I_H	holding current	$V_D = 12 \text{ V}; T_j = 25^\circ\text{C};$ Fig. 9		-	-	60	mA
V_T	on-state voltage	$I_T = 15 \text{ A}; T_j = 25^\circ\text{C};$ Fig. 10		-	1.3	1.6	V
V_{GT}	gate trigger voltage	$V_D = 12 \text{ V}; T_j = 25^\circ\text{C};$ Fig. 11		-	0.8	1	V
		$V_D = 400 \text{ V}; T_j = 150^\circ\text{C};$ Fig. 11		0.25	0.4	-	V
I_D	off-state current	$V_D = 800 \text{ V}; T_j = 150^\circ\text{C}$		-	0.4	2	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536 \text{ V}; T_j = 150^\circ\text{C}; (V_{DM} = 67\% \text{ of } V_{DRM});$ exponential waveform; gate open circuit		1000	-	-	V/ μ s
dI_{com}/dt	rate of change of commutating current	$V_D = 400 \text{ V}; T_j = 150^\circ\text{C}; I_{T(RMS)} = 10 \text{ A}; dV_{com}/dt = 20 \text{ V}/\mu\text{s};$ (snubberless condition); gate open circuit		20	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 150^\circ\text{C}; I_{T(RMS)} = 10 \text{ A}; dV_{com}/dt = 10 \text{ V}/\mu\text{s};$ gate open circuit		28	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 150^\circ\text{C}; I_{T(RMS)} = 10 \text{ A}; dV_{com}/dt = 1 \text{ V}/\mu\text{s};$ gate open circuit		45	-	-	A/ms

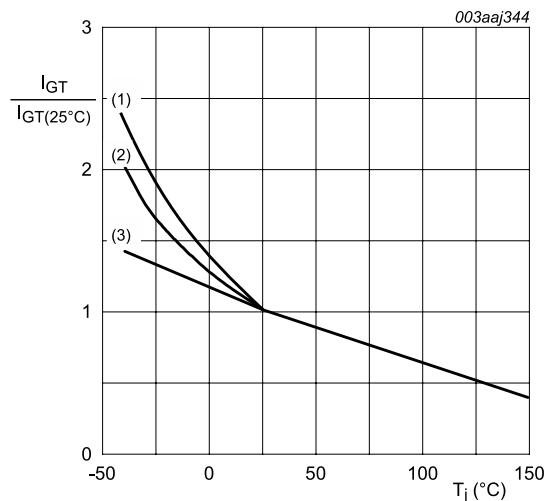


Fig. 7. Normalized gate trigger current as a function of junction temperature

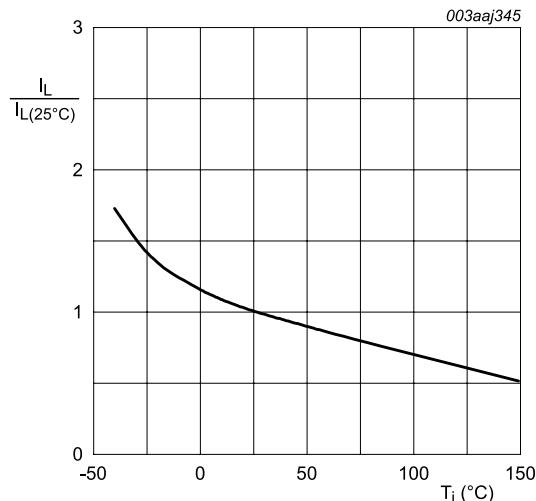


Fig. 8. Normalized latching current as a function of junction temperature

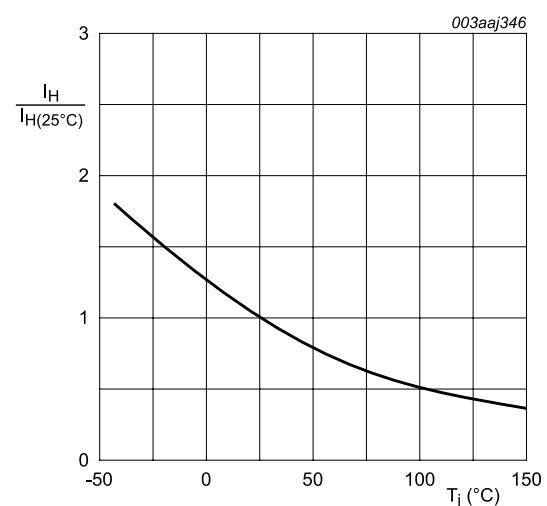


Fig. 9. Normalized holding current as a function of junction temperature

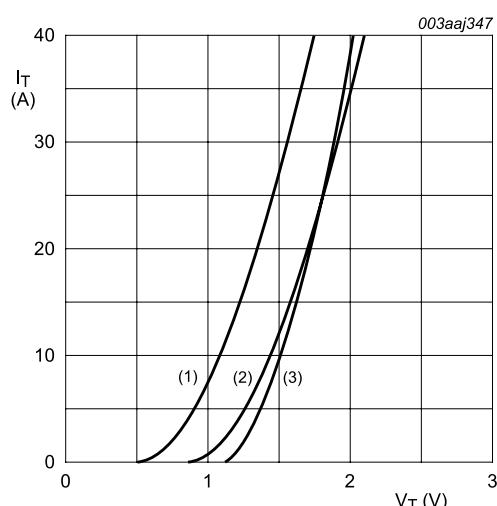


Fig. 10. On-state current as a function of on-state voltage

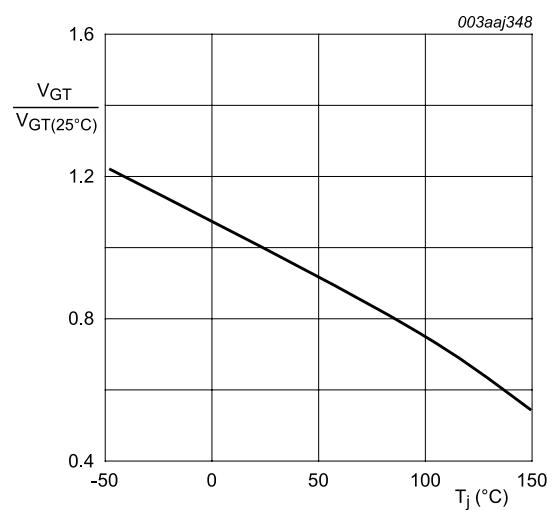
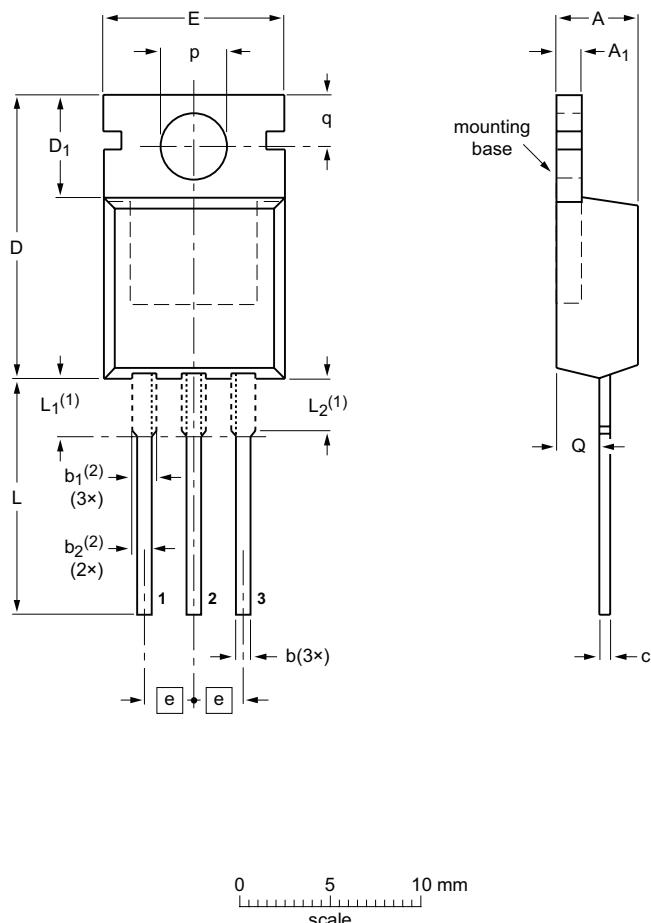


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

10. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



DIMENSIONS (mm are the original dimensions)

UNIT	A	A1	b	b ₁₍₂₎	b ₂₍₂₎	c	D	D ₁	E	e	L	L ₁₍₁₎	L ₂₍₁₎ max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

Notes

1. Lead shoulder designs may vary.
2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES					EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA				
SOT78		3-lead TO-220AB	SC-46				08-04-23 08-06-13